



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Blaine J. Thurgood

Serial No.: 10/685,312

Filed: October 14, 2003

For: INTERPOSER SUBSTRATES WITH
MULTISEGMENT INTERCONNECT
SLOTS, SEMICONDUCTOR, DIE
PACKAGES INCLUDING SAME,
SEMICONDUCTOR DICE FOR USE
THEREWITH AND METHODS OF
FABRICATION

Confirmation No.: 5043

Examiner: Unknown

Group Art Unit: 3726

Attorney Docket No.: 2269-5520.1US
(02-0676.01/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 19, 2005
Date

Signature

Joseph A. Walkowski
Name (Type/Print)

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 be considered by the Examiner and made of record. Copies of U.S. patents and U.S. patent publications are not being submitted pursuant to M.P.E.P. 609 III A(2). Copies of foreign patent documents and

non-patent literature are enclosed pursuant to 37 C.F.R. § 1.98(a)(2). The listed documents were cited by the Office in co-pending application Serial No. 10/409,804, filed on April 9, 2003, and directed to a related invention.

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicant herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

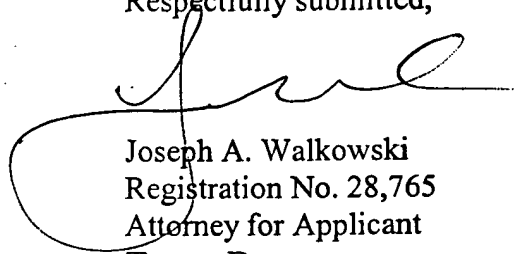
<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
US - 5,231,878	08/1993	Zanini-Fisher et al.
US - 2002/0008307 A1	01/2002	Dickey
US - 2002/0020689 A1	02/2002	Leung

Applicant offers to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

Serial No. 10/685,312

This Supplemental Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'J. Walkowski', is written over a large, stylized circular flourish.

Joseph A. Walkowski
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Date: January 19, 2005

JAW/dlm:ljb

Enclosures: Form PTO-1449 or PTO/SB/08

Document in ProLaw



Substitute for form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet

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of

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Complete if Known

Application Number	10/685,312
Filing Date	October 14, 2003
First Named Inventor	Blaine J. Thurgood
Group Art Unit	3726
Examiner Name	Unknown
Attorney Docket Number	2269-5520.1US (02-0676.01/US)

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
		US-5,231,878	08/1993	Zanini-Fisher et al.	
		US- 2002/0008307 A1	01/2002	Dickey	
		US- 2002/0020689 A1	02/2002	Leung	
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FOREIGN PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)				

Examiner
Signature

Date
Considered

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

THE PATENT & TRADEMARK OFFICE MAILROOM DA
STAMPED HEREON IS AN ACKNOWLEDGEMENT THAT ON THIS
DATE THE PATENT & TRADEMARK OFFICE RECEIVED

Supplemental Information Disclosure Statement (3 pages); and Form
PTO/SB/08 (1 page).

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